


MATERIAL DECLARATION SHEET

Material Number	TBU-CA Series			
Product Line	TBU Products			
Compliance Date	1/1/2010			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1.	Wafer	Silicon	3.941	Silicon	7440-21-3	100%	4.998504%	5.00%
2	Lead Frame	A194	36.717	Copper	7440-50-8	95.65%	46.568089%	48.69%
			0.837	Iron	7439-89-6	2.18%	1.061353%	
			0.012	Tin	7440-31-5	0.03%	0.014606%	
			0.050	Zinc	7440-66-6	0.13%	0.063292%	
			0.772	Silver	7440-22-4	2.01%	0.978587%	
3	Die-attach material	84LMISR4	0.039	Epoxy resin	Trade secret	2.99%	0.049126%	1.64%
			0.091	Functionalized ester	Trade secret	7.01%	0.115176%	
			0.039	Polymeric compound	Trade secret	2.99%	0.049126%	
			1.127	Silver	7440-22-4	87.01%	1.429591%	
4	Gold Bond wire	Gold	0.188	Gold	7440-57-5	100%	0.237890%	0.24%

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5	Mold compound	G770	29.525	Silica fused	60676-86-0	90.49%	37.446126%	41.38%
			1.534	Epoxy resin	Trade Secret	4.70%	1.944931%	
			1.534	Phenol resin	Trade Secret	4.70%	1.944931%	
			0.036	Carbon black	1333-86-4	0.11%	0.045520%	
6	Tin plating	Tin	2.407	Tin	7440-31-5	100%	3.053152%	3.05%
Total weight			78.846 mg					

This Document was updated on: 14-May-2010

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.